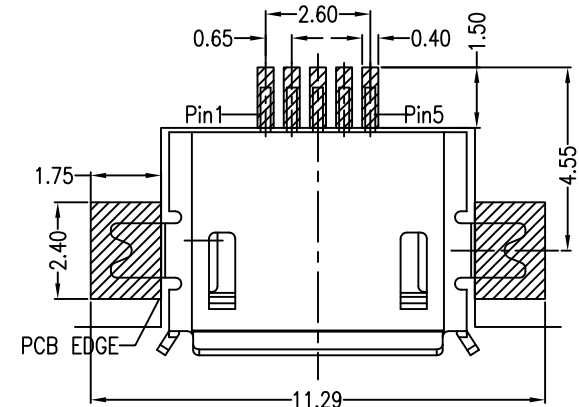
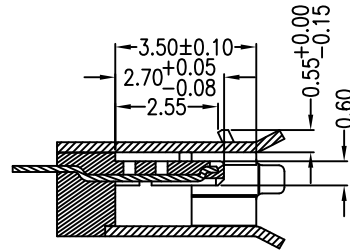
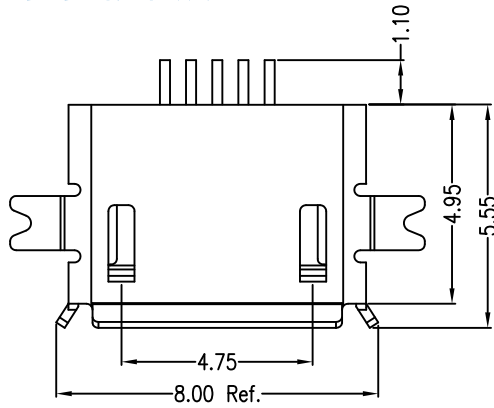
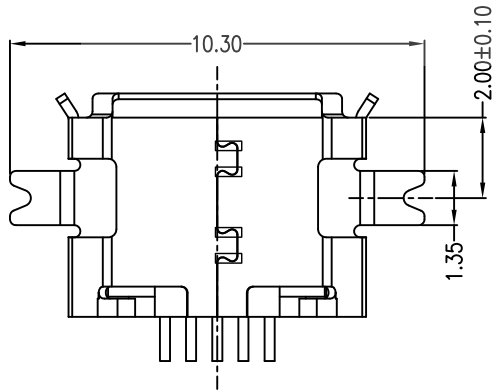
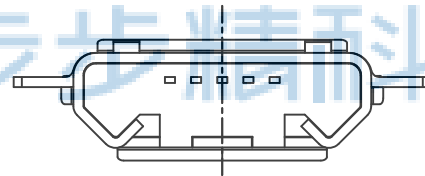
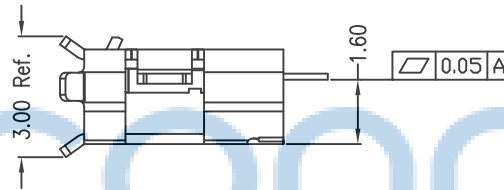
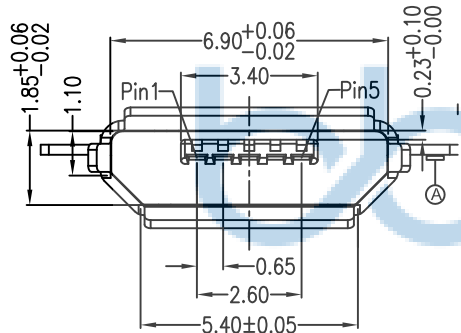


REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0			2023 20/04	



RECOMMENDED PCB LAYOUT
PCB图仅供参考



Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.15mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

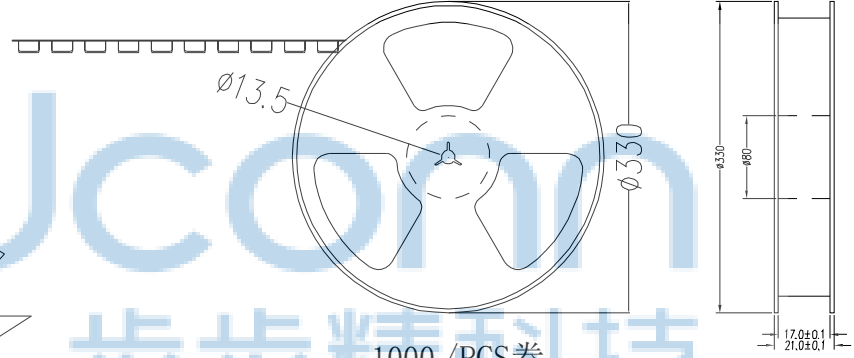
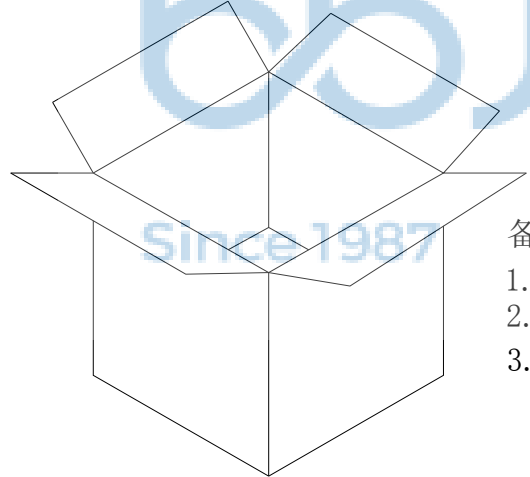
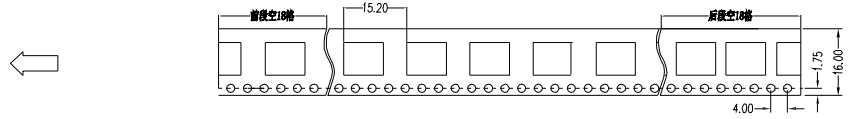
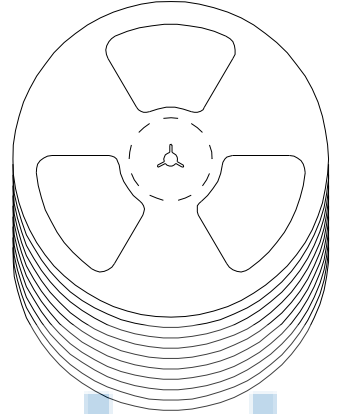
- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -30°C~80°C

Since 1987

步步精科技



THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co.,Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司 工程部 APPROVED BBJconn Technology Co., Ltd.	
PDWG.NO: 0113-1	DR. SGF	.X: ±0.38 .XX: ±0.25 .XXX: ±0.13 X*: ±3* .X*: ±2* .XX*: ±1*	NAME: MICRO-5P BF 沉板1.6 L=5.55 俩脚全贴 卷边 雾锡 铜壳 APPD. JM_Zheng 23/05'02 CHKD. LYX 23/05'02 23/05'02 PJ. NO.: MC.01.71-11-1004 SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1



备注：
1. 包装数量：1000 /PCS/卷，10卷/箱或15卷/箱。
2. 包装袋长度：每卷前后各空10-20个空格，中间包装。
3. 材质：
载体：聚丙烯（PS），阻抗 $10^{6-9} \Omega$
上带：聚乙烯（PET），阻抗 $10^{6-11} \Omega$
卷盘：聚苯乙烯。
纸箱规格：345*345*23MM
纸箱规格：345*345*35MM



THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co.,Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司 .X: ±0.38 .X': ±3" .XX: ±0.25 .X'': ±2" .XXX: ±0.13 .XX': ±1"		NAME: MICRO-5P BF 沉板1.6 L=5.55 俩脚全贴 卷边 雾锡 铜壳 PJ. NO.: MC.01.71-11-1004 SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1	
APPD.	JM_Zheng	23/05'02			
CHKD.	LYX	23/05'02			
PDWG.NO:	0113-1	DR.	SGF	23/05'02	